



Material Composition Declaration

EPC2101

Company Name	Efficient Power Conversion (EPC)	Issue Date:	3/14/2018
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	23.0 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	19.9310	86.6477	89.2933	866477
	Silicon oxide	7631-86-9	0.0896	0.3894		3894
	Silicon nitride	12033-89-5	0.0321	0.1394		1394
	Gallium nitride	25617-97-4	0.1029	0.4474		4474
	Aluminum	7429-90-5	0.1562	0.6792		6792
	Aluminum nitride	24304-00-5	0.0248	0.1080		1080
	Titanium	7440-32-6	0.0042	0.0181		181
	Titanium nitride	25583-20-4	0.0144	0.0626		626
	Copper	7440-50-8	0.0052	0.0226		226
	Tungsten	7440-33-7	0.0061	0.0265		265
	Polyimide		0.1731	0.7524		7524
Under Bump Metal	Titanium	7440-32-6	0.0015	0.0065	0.5505	65
	Nickel	7440-02-0	0.0000	0.0000		0
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.1251	0.5440		5440
Solder Bump	Tin	7440-31-5	2.2310	9.6992	10.1562	96992
	Silver	7440-22-4	0.0934	0.4062		4062
	Copper	7440-50-8	0.0117	0.0508		508
Sum in total:			23.0023	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.